



DPW

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: **Miwa KOZAWA et al.**

Art Unit: **1756**

Application Number: **10/670,291**

Examiner: **Daborah Chacko-Davis**

Filed: **September 26, 2003**

Confirmation Number: **6427**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR FORMING  
RESIST PATTERN, AND PROCESS FOR MANUFACTURING  
SEMICONDUCTOR DEVICE**

Attorney Docket Number: **031181**

Customer Number: **38834**

**REQUEST FOR RECONSIDERATION**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

July 25, 2008

Sir:

This paper is filed in response to the Office Action dated May 1, 2008.

Remarks begin on page 2 of this paper.